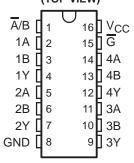
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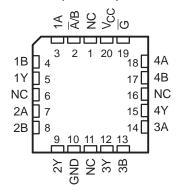
- Wide Operating Voltage Range of 2 V to 6 V
- **High-Current Inverting Outputs Drive Up To** 15 LSTTL Loads
- Low Power Consumption, 80-µA Max I_{CC}
- 'HC257 . . . Typical $t_{pd} = 9 \text{ ns}$

SN54HC257, SN54HC258...J PACKAGE SN74HC257, SN74HC258 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- 'HC258 . . . Typical t_{pd} = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- **Provides Bus Interface from Multiple** Sources in High-Performance Systems

SN54HC257, SN54HC258...FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

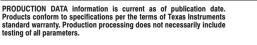
ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DDID N	Tub (05	SN74HC257N	SN74HC257N
	PDIP – N	Tube of 25	SN74HC258N	SN74HC258N
		Tube of 40	SN74HC257D	
		Reel of 2500	SN74HC257DR	HC257
	SOIC - D Reel of 250		SN74HC257DT	
		Tube of 40	SN74HC258D	110050
		Reel of 2500	SN74HC258DR	HC258
-40°C to 85°C	00D NO	D1 - (0000	SN74HC257NSR	HC257
	SOP – NS	Reel of 2000	SN74HC258NSR	HC258
		Tube of 90	SN74HC257PW	
		Reel of 2000	SN74HC257PWR	HC257
	T0000 514/	Reel of 250	SN74HC257PWT	
	TSSOP – PW	Tube of 90	SN74HC258PW	
		Reel of 2000	SN74HC258PWR	HC258
		Reel of 250	SN74HC258PWT	
	CDID I	Tube of OF	SNJ54HC257J	SNJ54HC257J
5500 to 40500	CDIP – J	Tube of 25	SNJ54HC258J	SNJ54HC258J
–55°C to 125°C	LCCC – FK	Tubo of FF	SNJ54HC257FK	SNJ54HC257FK
	LCCC - FK	Tube of 55	SNJ54HC258FK	SNJ54HC258FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

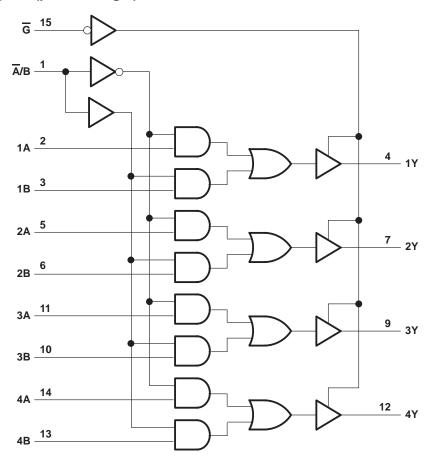
These devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{G}) input is at a high logic level.

To ensure the high-impedance state during power up or power down, \overline{G} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

	INPL	JTS		OUTPUT Y				
G	A/B	Α	В	'HC257	'HC258			
Н	Χ	Χ	Χ	Z	Z			
L	L	L	X	L	Н			
L	L	Н	X	Н	L			
L	Н	Χ	L	L	Н			
L	Н	Χ	Н	Н	L			

'HC257 logic diagram (positive logic)

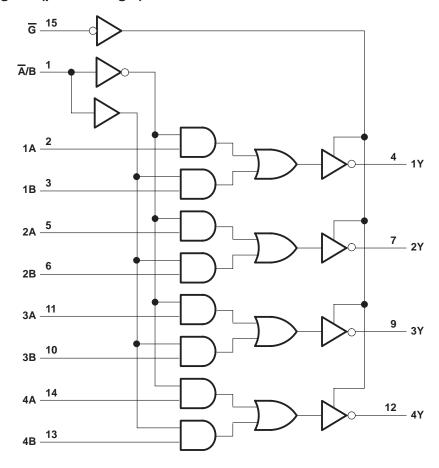


Pin numbers shown are for the D, J, N, NS, and PW packages.



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'HC258 logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and PW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$).		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ _{JA} (see Note 1):	: D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 2)

				154HC25 N54HC25			74HC25 174HC25	•	UNIT
			MIN	NOM	MAX	MIN	NOM	NOM MAX	
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
\vee_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.3			0.5	
٧ _{IL}	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$			0.9			1.35	V
		VCC = 6 V			1.2			1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	VCC	Т	A = 25°C	;	SN54H SN54H		SN74HC257, SN74HC258		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			2 V	1.9	1.998		1.9		1.9			
		$I_{OH} = -20 \mu A$	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Vон	$V_I = V_{IH}$ or V_{IL}		6 V	5.9	5.999		5.9		5.9		V	
		I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7		3.84			
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
			2 V		0.002	0.1		0.1		0.1		
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1		
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V	
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33		
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33		
ΙĮ	$V_I = V_{CC}$ or 0	•	6 V		±0.1	±100		±1000		±1000	nA	
loz	$V_O = V_{CC}$ or 0	•	6 V		±0.01	±0.5		±10		±5	μΑ	
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ	
C _i			2 V to 6 V		3	10		10		10	pF	

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

	FROM	то	.,	T,	ղ = 25°C	;	SN54H	C257	SN74H	C257	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		50	100		150		125	
	A or B	Any Y	4.5 V		10	20		30		25	
			6 V		9	17		25		21	
^t pd			2 V		50	100		150		125	ns
	Ā/B	Any Y	4.5 V		10	20		30		25	
			6 V		9	17		25		21	
			2 V		75	150		225		190	
^t en	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		75	150		225		190	
^t dis	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		28	60		90		75	
t _t		Any Y	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

	FROM	то		T,	Δ = 25°C	;	SN54H	C257	SN74H	C257	
PARAMETER	(INPUT)	(OUTPUT)	vcc	VCC MIN TYP MA			MIN	MAX	MIN MAX		UNIT
			2 V		75	150		245		190	
	A or B	Any Y	4.5 V		15	30		45		38	
			6 V		13	26		38		32	
^t pd			2 V		75	150		245		190	ns
	Ā/B	Any Y	4.5 V		15	30		45		38	
			6 V		13	26		38		32	
			2 V		100	200		300		250	
t _{en}	G	Any Y	4.5 V		24	40		60		50	ns
			6 V		18	34		51		43	
			2 V		45	210		315		265	
t _t		Any Y	4.5 V		17	42		63		53	ns
			6 V		13	36		53		45	

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

242445	FROM	то	.,	T	λ = 25°C	;	SN54H	C258	SN74HC258												
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT										
			2 V		60	100		150		125											
	A or B	Any Y	4.5 V		13	20		30		25											
			6 V		12	17		25		21											
^t pd			2 V		60	115		175		145	ns										
	Ā/B	Any Y	4.5 V		13	23		35		29											
			6 V		12	20		30		25											
			2 V		70	150		225		190											
^t en	G	Any Y	4.5 V		15	30		45		38	ns										
			6 V		13	26		38		32											
			2 V		75	150		225		190											
^t dis	G	Any Y	4.5 V		15	30		45		38	ns										
			6 V		13	26		38		32											
			2 V		28	60		90		75											
t _t	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	Any Y	4.5 V		8	12		18		15	ns
			6 V	_	6	10	_	15		13											

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

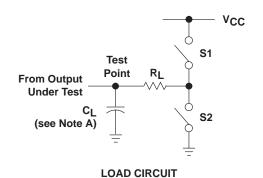
242445	FROM	то	l .,	T,	\ = 25°C	;	SN54H	IC258	SN74H	C258				
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT			
			2 V		95	150		245		190				
	A or B	Any Y	4.5 V		23	30		45		38				
,			6 V		21	26		38		32				
^t pd			2 V		95	165		240		210	ns			
	Ā/B	Any Y	4.5 V		23	33		48		42				
			6 V		21	28		41		36				
			2 V		100	200		300		250				
t _{en}	G	Any Y	4.5 V		24	40		60		50	ns			
			6 V		18	34		51		43				
			2 V		45	210		315		265				
t _t	t _t	Any Y	Any Y	Any Y	Any Y	4.5 V		17	42		63		53	ns
			6 V		13	36	_	53		45				

operating characteristics, T_A = 25°C

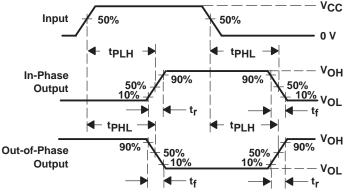
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per multiplexer	No load	40	pF

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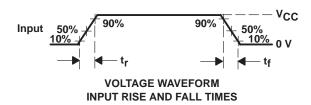
PARAMETER MEASUREMENT INFORMATION

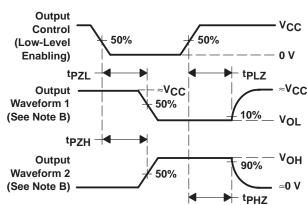


PARAI	METER	RL	CL	S1	S2	
	tPZH	1 k Ω	50 pF or	Open	Closed	
^t en	tPZL	1 K22	150 pF	Closed	Open	
4	tPHZ	1 k Ω	50 pF	Open	Closed	
^t dis	tPLZ	1 K22	30 pr	Closed	Open	
t _{pd} or t _t			50 pF or 150 pF	Open	Open	



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES





VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
85124012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85124012A SNJ54HC 257FK	Samples
8512401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8512401EA SNJ54HC257J	Samples
SN54HC257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC257J	Samples
SN74HC257DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC257	Samples
SN74HC257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC257N	Samples
SN74HC257NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257	Samples
SN74HC257PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC257	Samples
SN74HC258D	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258	
SN74HC258DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258	Samples
SN74HC258N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC258N	Samples
SN74HC258NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258	Samples
SN74HC258PW	LIFEBUY	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258	
SN74HC258PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258	Samples
SNJ54HC257FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85124012A SNJ54HC 257FK	Samples
SNJ54HC257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8512401EA SNJ54HC257J	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC257, SN74HC257:

Catalog: SN74HC257

Military: SN54HC257

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO PI BO Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC257NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC257NSR	so	NS	16	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HC257PWR	TSSOP	PW	16	2000	330.0	12.4	6.85	5.45	1.6	8.0	12.0	Q1
SN74HC257PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC257PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC258DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC258NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC258PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

7 ili dilliciololio die fiorilliai							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC257DR	SOIC	D	16	2500	356.0	356.0	35.0
SN74HC257NSR	so	NS	16	2000	356.0	356.0	35.0
SN74HC257NSR	so	NS	16	2000	356.0	356.0	35.0
SN74HC257PWR	TSSOP	PW	16	2000	366.0	364.0	50.0
SN74HC257PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC257PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC258DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC258NSR	SO	NS	16	2000	356.0	356.0	35.0
SN74HC258PWR	TSSOP	PW	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

All difficultions are norminal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
85124012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74HC257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258D	D	SOIC	16	40	507	8	3940	4.32
SN74HC258N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258PW	PW	TSSOP	16	90	530	10.2	3600	3.5
SNJ54HC257FK	FK	LCCC	20	1	506.98	12.06	2030	NA



SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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